# **BLP10H603**

## **Broadband LDMOS driver transistor**

**AMMPLEON** Rev. 2 — 1 September 2015 Product data sheet

## **Product profile** 1.

## 1.1 General description

A 2.5 W plastic LDMOS power transistor for broadcast transmitter and ISM applications at frequencies from HF to 1400 MHz.

Table 1. **Application performance** 

| Test signal | f     | V <sub>DS</sub> | $P_L$ | Gp   | η <sub>D</sub> |
|-------------|-------|-----------------|-------|------|----------------|
|             | (MHz) | (V)             | (W)   | (dB) | (%)            |
| CW          | 860   | 50              | 2.5   | 22.8 | 62             |

### 1.2 Features and benefits

- Easy power control
- Integrated ESD protection
- Excellent ruggedness
- High efficiency
- Excellent thermal stability
- Designed for broadband operation (HF to 1400 MHz)
- Compliant to Directive 2002/95/EC, regarding Restriction of Hazardous Substances (RoHS)

## 1.3 Applications

- Industrial, scientific and medical applications
- Broadcast transmitter applications

### **Broadband LDMOS driver transistor**

## 2. Pinning information

Table 2. Pinning

| Pin                               | Description | Simplified outline | Graphic symbol   |
|-----------------------------------|-------------|--------------------|------------------|
| 1, 2, 4, 5, 6, 7, 8, 9,<br>11, 12 | n.c.        | 1 12               | 10               |
| 3                                 | gate1       | 2           11     |                  |
| 10                                | drain1      |                    | 3 —              |
| 13                                | source [1]  | 4                  | 13<br>aaa-012010 |

[1] Connected to flange.

## 3. Ordering information

Table 3. Ordering information

| Type number | Package |  |           |  |  |
|-------------|---------|--|-----------|--|--|
|             | Name    | lame Description   |           |  |  |
| BLP10H603   |         | plastic thermal enhanced very thin small outline package; no leads; 12 terminals; body $5\times6\times0.85$ mm | SOT1352-1 |  |  |

## 4. Limiting values

Table 4. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134).

| Symbol           | Parameter            | Conditions | Min | Max  | Unit |
|------------------|----------------------|------------|-----|------|------|
| $V_{DS}$         | drain-source voltage |            | -   | 104  | V    |
| $V_{GS}$         | gate-source voltage  |            | -6  | +11  | V    |
| T <sub>stg</sub> | storage temperature  |            | -65 | +150 | °C   |
| T <sub>i</sub>   | junction temperature |            | -   | 150  | °C   |

### **Broadband LDMOS driver transistor**

## 5. Recommended operating conditions

See application note AN11520 for more details.

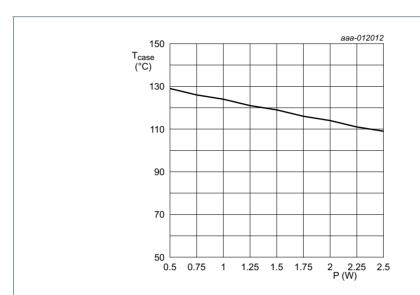


Fig 1. Recommended operating area; case temperature as a function of power dissipation

## 6. Thermal characteristics

Table 5. Thermal characteristics

| Sy | mbol   | Parameter                                | Conditions  | Тур | Unit |
|----|--------|--|---|-----|------|
| Rt | h(j-c) | thermal resistance from junction to case | $T_{case} = 80  ^{\circ}C; P_{L} = 2.5  W  ^{11}$ | 9.9 | K/W  |

<sup>[1]</sup>  $R_{th(j-c)}$  is measured under RF conditions

## 7. Characteristics

Table 6. DC characteristics

 $T_j = 25$  °C; unless otherwise specified.

| Symbol               | Parameter                        | Conditions   | Min  | Тур  | Max  | Unit |
|----------------------|----------------------------------|--|------|------|------|------|
| V <sub>(BR)DSS</sub> | drain-source breakdown voltage   | $V_{GS} = 0 \text{ V}; I_D = 0.03 \text{ mA}$                      | 104  | -    | -    | V    |
| V <sub>GS(th)</sub>  | gate-source threshold voltage    | $V_{DS} = 10 \text{ V}; I_D = 3 \text{ mA}$                        | 1.25 | 1.65 | 2.25 | V    |
| $V_{GSq}$            | gate-source quiescent voltage    | $V_{DS} = 50 \text{ V}; I_{D} = 15 \text{ mA}$                     | 1.3  | 1.73 | 2.15 | V    |
| I <sub>DSS</sub>     | drain leakage current            | V <sub>GS</sub> = 0 V; V <sub>DS</sub> = 50 V                      | -    | -    | 1.4  | μА   |
| I <sub>DSX</sub>     | drain cut-off current            | $V_{GS} = V_{GS(th)} + 3.75 \text{ V};$<br>$V_{DS} = 10 \text{ V}$ | -    | 0.5  | -    | Α    |
| $I_{GSS}$            | gate leakage current             | $V_{GS} = 11 \text{ V}; V_{DS} = 0 \text{ V}$                      | -    | -    | 140  | nA   |
| R <sub>DS(on)</sub>  | drain-source on-state resistance | $V_{GS} = V_{GS(th)} + 3.75 \text{ V};$<br>$I_D = 105 \text{ mA}$  | -    | 9    | -    | Ω    |

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Table 7. AC characteristics

 $T_i = 25$  °C; unless otherwise specified.

| Symbol           | Parameter            | Conditions   | Min | Тур  | Max | Unit |
|------------------|----------------------|--|-----|------|-----|------|
| C <sub>rs</sub>  | feedback capacitance | $V_{GS} = 0 \text{ V}; V_{DS} = 50 \text{ V}; f = 1 \text{ MHz}$ | -   | 0.03 | -   | pF   |
| C <sub>iss</sub> | input capacitance    | $V_{GS} = 0 \text{ V}; V_{DS} = 0 \text{ V}; f = 1 \text{ MHz}$  | -   | 3.4  | -   | pF   |
| C <sub>oss</sub> | output capacitance   | V <sub>GS</sub> = 0 V; V <sub>DS</sub> = 50 V; f = 1 MHz         | -   | 1.12 | -   | pF   |

#### Table 8. RF characteristics

Test signal: pulsed CW; f = 860 MHz; RF performance at  $V_{DS} = 50$  V;  $I_{Dq} = 15$  mA;  $t_p = 50$   $\mu$ s;  $\delta = 10$  %;  $T_{case} = 25$  °C; unless otherwise specified, in a class-AB production test circuit [1].

| Symbol     | Parameter        | Conditions             | Min  | Тур  | Max  | Unit |
|------------|------------------|------------------------|------|------|------|------|
| Gp         | power gain       | P <sub>L</sub> = 2.5 W | 21.4 | 22.8 | 25.5 | dB   |
| $\eta_{D}$ | drain efficiency | P <sub>L</sub> = 2.5 W | 60   | 62   | -    | %    |

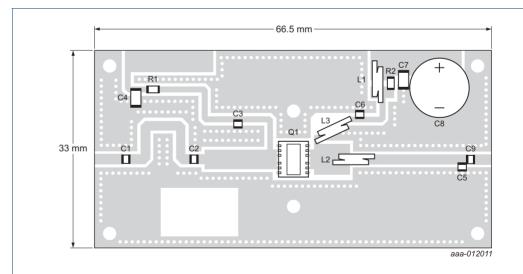
<sup>[1]</sup> The industrial test method is performed on special hardware to accommodate the requirements of production. The test results in this table are correlated to correspond with a performance in the application.

## 8. Test information

## 8.1 Ruggedness in class-AB operation

The BLP10H603 is capable of withstanding a load mismatch corresponding to VSWR = 35 : 1 through all phases under the following conditions:  $V_{DS}$  = 50 V;  $I_{Dq}$  = 15 mA;  $P_{L}$  = 2.5 W; f = 860 MHz.

#### 8.2 Test circuit



Printed-Circuit Board (PCB): Rogers RO4350;  $\epsilon_{\text{r}}$  = 3.48; height = 0.762 mm; thickness copper plating = 35  $\mu$ m.

See Table 9 for a list of components.

#### Fig 2. Component layout

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Table 9. List of components See Figure 2 for component layout.

| Component      | Description                       | Value              |            | Remarks                   |
|----------------|-----------------------------------|--------------------|------------|---------------------------|
| C1, C3, C6, C9 | multilayer ceramic chip capacitor | 100 pF             | [1]        |                           |
| C2             | multilayer ceramic chip capacitor | 3.9 pF             | [1]        |                           |
| C4             | multilayer ceramic chip capacitor | 1 μF, 25 V         |            | Murata GRM31MR71E105KA01L |
| C5             | multilayer ceramic chip capacitor | 4.7 pF             | <u>[1]</u> |                           |
| C7             | multilayer ceramic chip capacitor | 1 μF, 50 V         |            | Murata GRM32RR71H105KA01L |
| C8             | electrolytic capacitor            | 220 μF, 63 V       |            |                           |
| L1             | wire inductor, 0.8 mm copper wire | 2 turn, D = 3 mm   |            |                           |
| L2             | wire inductor, 0.8 mm copper wire | 2 turn, D = 2.7 mm |            |                           |
| L3             | wire inductor, 0.8 mm copper wire | 2 turn, D = 3 mm   |            |                           |
| R1             | resistor                          | 0 Ω                |            | SMD 0805                  |
| R2             | resistor                          | 10 Ω               |            | SMD 0805                  |
| Q1             | transistor                        | -                  |            | BLP10H603                 |

<sup>[1]</sup> American Technical Ceramics type 100A or capacitor of same quality.

## 8.3 Graphical data

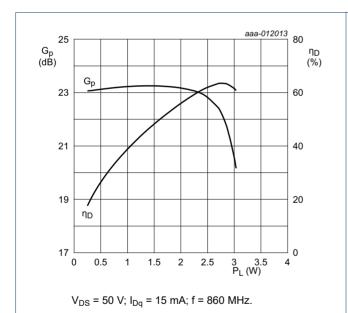
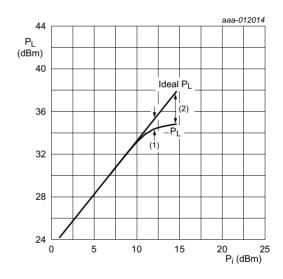


Fig 3. Power gain and drain efficiency as function of output power; typical values

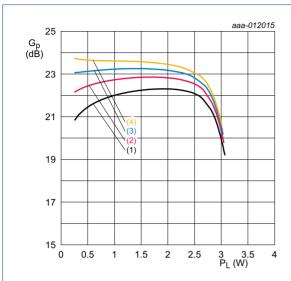


 $V_{DS} = 50 \text{ V}; I_{Dq} = 15 \text{ mA}; f = 860 \text{ MHz}.$ 

- (1)  $P_{L(1dB)} = 34.4 \text{ dBm } (2.8 \text{ W})$
- (2)  $P_{L(3dB)} = 34.8 \text{ dBm } (3.0 \text{ W})$

Fig 4. Output power as a function of input power; typical values

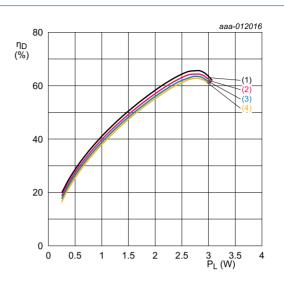
### **Broadband LDMOS driver transistor**



 $V_{DS} = 50 \text{ V}$ ; f = 860 MHz.

- (1)  $I_{Dq} = 5 \text{ mA}$
- (2)  $I_{Dq} = 10 \text{ mA}$
- (3)  $I_{Dq} = 15 \text{ mA}$
- (4)  $I_{Dq} = 20 \text{ mA}$

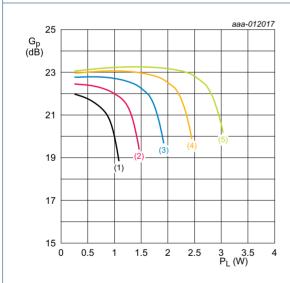
Fig 5. Power gain as a function of output power; typical values



 $V_{DS} = 50 \text{ V}; f = 860 \text{ MHz}.$ 

- (1)  $I_{Dq} = 5 \text{ mA}$
- (2)  $I_{Dq} = 10 \text{ mA}$
- (3)  $I_{Dq} = 15 \text{ mA}$
- (4)  $I_{Dq} = 20 \text{ mA}$

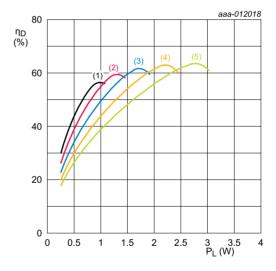
Fig 6. Drain efficiency as a function of output power; typical values



 $I_{Dq} = 15 \text{ mA}$ ; f = 860 MHz.

- (1)  $V_{DS} = 30 \text{ V}$
- (2)  $V_{DS} = 35 \text{ V}$
- (3)  $V_{DS} = 40 \text{ V}$
- (4)  $V_{DS} = 45 \text{ V}$
- (5)  $V_{DS} = 50 \text{ V}$

Fig 7. Power gain as a function of output power; typical values



 $I_{Dq} = 15 \text{ mA}$ ; f = 860 MHz.

- (1)  $V_{DS} = 30 \text{ V}$
- (2)  $V_{DS} = 35 V$
- (3)  $V_{DS} = 40 \text{ V}$
- (4)  $V_{DS} = 45 \text{ V}$
- (5)  $V_{DS} = 50 \text{ V}$

Fig 8. Drain efficiency as a function of output power; typical values

### **Broadband LDMOS driver transistor**

## 9. Package outline

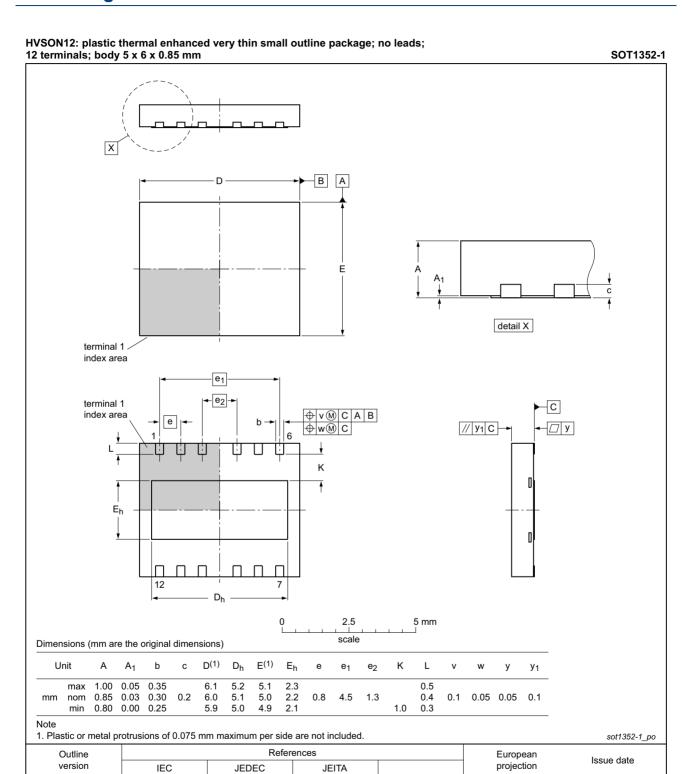


Fig 9. Package outline SOT1352-1 (HVSON12)

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13-03-26

13-07-16

SOT1352-1

### **Broadband LDMOS driver transistor**

## 10. Handling information

### CAUTION



This device is sensitive to ElectroStatic Discharge (ESD). Observe precautions for handling electrostatic sensitive devices.

Such precautions are described in the ANSI/ESD S20.20, IEC/ST 61340-5, JESD625-A or equivalent standards.

## 11. Abbreviations

Table 10. Abbreviations

| Acronym | Description                                  |  |
|---------|--|--|
| CW      | Continuous Wave                              |  |
| ESD     | ElectroStatic Discharge                      |  |
| LDMOS   | Laterally Diffused Metal-Oxide Semiconductor |  |
| HF      | High Frequency                               |  |
| ISM     | Industrial, Scientific and Medical           |  |
| SMD     | Surface Mounted Device                       |  |
| VSWR    | Voltage Standing-Wave Ratio                  |  |

## 12. Revision history

Table 11. Revision history

| Document ID    | Release date   | Data sheet status  | Change notice | Supersedes    |  |
|----------------|--|--------------------|---------------|---------------|--|
| BLP10H603#2    | 20150901   | Product data sheet |               | BLP10H603 v.1 |  |
| Modifications: | The format of this document has been redesigned to comply with the new identity guidelines of Ampleon. |                    |               |               |  |
|                | <ul> <li>Legal texts have been adapted to the new company name where appropriate.</li> </ul>           |                    |               |               |  |
| BLP10H603 v.1  | 20141002   | Product data sheet | -             | -             |  |

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| Document status[1][2]          | Product status[3] | Definition  |
|--------------------------------|-------------------|---|
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